

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ming-Hsi Yeh	08/30/2011
Kuo-Sheng Chuang	08/30/2011
Ying-Hsueh Chang Chien	08/30/2011
Chi-Ming Yang	08/30/2011
Chin-Hsiang Lin	08/30/2011
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13210998
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	24061.1863/2011-0555

OP \$40.00 13210998

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PATENT
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NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------------|----|---|
| (1) | Ming-Hsi Yeh | of | 6F, 6, Ching-San St. 28
Hsinchun, Taiwan (R.O.C.) |
| (2) | Kuo-Sheng Chuang | of | 6F., No.19, Ln. 188, Dongnan St.
East Dist., Hsinchu City 300, Taiwan (R.O.C.) |
| (3) | Ying-Hsueh Chang Chien | of | 24F., No.263, Sec. 2, Datong Rd.
Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.) |
| (4) | Chi-Ming Yang | of | 4, Lane 67, Duan-Feng Rd.
Hsian-San District, Taiwan 300-77 (R.O.C.) |
| (5) | Chin-Hsiang Lin | of | No. 37, Lane 393, Min-hu Road
Hsin-chu, Taiwan (R.O.C.) |

have invented certain improvements in

SEMICONDUCTOR DEVICE CLEANING METHOD AND APPARATUS

for which we have executed an application for Letters Patent of the United States of America, filed on August 16, 2011 and assigned application number 13/210,998; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ming-Hsi Yeh
Residence Address: 6F, 6, Ching-San St. 28
Hsinchun, Taiwan (R.O.C.)

Dated: 8/30'2011 Ming-Hsi Yeh
Inventor Signature

Inventor Name: Kuo-Sheng Chuang
Residence Address: 6F., No.19, Ln. 188, Dongnan St.
East Dist., Hsinchu City 300, Taiwan (R.O.C.)

Dated: 8/30'2011 Kuo-Sheng, Chuang
Inventor Signature

Inventor Name: Ying-Hsueh Chang Chien
Residence Address: 24F., No.263, Sec. 2, Datong Rd.
Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

Dated: 8/30'2011 Ying-Hsueh Chang Chien
Inventor Signature

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Inventor Name: Chi-Ming Yang

Residence Address: 4, Lane 67, Duan-Feng Rd.
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Dated: 8/30, 2011

Chi-Ming Yang
Inventor Signature

Inventor Name: Chin-Hsiang Lin

Residence Address: No. 37, Lane 393, Min-hu Road
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Dated: 8/30, 2011

Chin-Hsiang Lin
Inventor Signature